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Session I-a Materials & Processing (1)

P060*	Recent Advances in Anisotropic Conductive Adhesives (ACAs) Technology: Materials and Processing ""3 <i>Kyung W. Paik</i> <i>Korea Advanced Institute of Science and Technology, KOREA</i>
<i>P034</i> ⁺	Potential-assisted Assembly of Thiol-based Materials for Reliable Copper-Epoxy Interface "6 Stephen C.T. KWOK, Matthew M.F. YUEN Department of Mechanical Engineering, The Hong Kong University of Science and Technology, HONG KONG
<i>P043</i> ⁺	Preparation of MWCNT-Ni0.5Zn0.5Fe2O4-Epoxy Composites with both Dielectric and Ferromagnetic Properties "; <i>Qi Zheng</i> , ^{1,2} <i>Pengli Zhu</i> , ^{1*} <i>Rong Sun</i> , ^{1*} , <i>Ching-Ping Wong</i> ³ ¹ <i>Shenzhen Institutes of Advanced Technology, Chinese Academy of Science, CHINA</i> ² <i>Shenzhen University, CHINA</i> ³ <i>Department of Electronics Engineering, The Chinese University of Hong Kong, HONG</i> <i>KONG</i>
<i>P046</i>	Joint Properties of Micro Sn-58Bi Solder Bumps on Flexible Substrate "35 Min-Su Kim ^{1, 2} , Yong-Ho Ko ^{2, 3} , Sehoon Yoo ² , Chang-Woo Lee ² ¹ Dept. of Electronic Packaging Engineering, University of Science & Technology, KOREA ² Micro-Joining Center, Korea Institute of Industrial Technology, KOREA ³ Dept. of Mechanical Engineering, KAIST, KOREA
P030*	Controlling Fusion Zone Shape and Peak Temperature Produced by Laser or Electron Beam""39 P. S. Wei Department of Mechanical and Electro-Mechanical Engineering National Sun Yat-Sen University, TAIWAN
P100	Improvement of Pick & Place Yield in Carrier Tape Packaging System through Materials Selection and Cavity Structure Optimization""42 Chenxiao Qiao ¹ , Yuning Shi ³ , Nelson G. Vicera ³ , Matthew Poon ³ , Weiqiang Li ¹ , Haibin Chen ^{1, 2,} Jingshen Wu ^{1,2} ¹ Department of Mechanical Engineering, The Hong Kong University of Science and Technology, HONG KONG ² Center of Engineering Materials and Reliability, HKUST Fok Ying Tung Graduate School, The Hong Kong University of Science and Technology, HONG KONG ³ NXP Semiconductors Hong Kong Ltd, Kowloon, Hong Kong
<i>P101</i> ⁺	Effects of Moisture Absorption and Temperature on the Adhesion Strength between Die Attach Film (DAF) and Silicon Die""46 Chunhua Guan ¹ , Martin Li ² , Kewei Chen ² , Haibin Chen ^{1, 3} , Jingshen Wu ^{1, 3} ¹ Center of Engineering Materials and Reliability, Fok Ying Tung Graduate School, Hong Kong University of Science and Technology, HONG KONG ² NXP Semiconductors Hong Kong Ltd, HONG KONG ³ Department of Mechanical Engineering, Hong Kong University of Science and Technology, HONG KONG
<i>P020</i>	Photo-mask Cleaning issues at Photolithography of Bumping Process(For Packaging) ""P IC Ted Miyagawa Technovision Inc., Kawajima-machi Saitama, JAPAN
<i>P075</i>	Electrochemical deposition of Galfenol "4: Robert W. Kay ¹ , Jack Ng ² , Marc P. Y. Desmulliez ² , Chris Popov ² , Paul Record ² ¹ Additive Manufacturing Research Group (AMRG), Loughborough University, UK ² MicroSystems Engineering Centre (MiSEC), Heriot-Watt University, UK

Session I-b Design & Applications

<i>P072*</i>	Thin Packages Enabling Thin Mobile Products "54 William T. Chen, Andy Tseng, Bernd K. Appelt ASE Group, Sunnyvale, USA
P038*	Air Gap Design of Current Sensor Based on Closed Loop Hall Effect "59 Fu'an Li ^{1,2} , Xingguo Cheng ^{2,3} , Sheng Liu ^{2,3} , Xiaobing Luo ^{1,2} ¹ School of Energy and Power Engineering, Huazhong University of Science and Technology, CHINA ² Wuhan National Lab for Optoelectronics, Huazhong University of Science and Technology, CHINA ³ Institute of Microsystems, State Key Laboratory for Digital Manufacturing Equipment & Technology, School of Mechanical Science and Engineering, Huazhong University of Sci & Tech, CHINA
P121	Generation of Arbitrary Vector Beams with a Spatial Light Modulator 64 Mengnan Zhao, Xiangsheng Xie State Key Laboratory of Optoelectric Material and Technology, Sun Yat-Sen University, CHINA
<i>P078</i>	Optical Module for Healthcare Electronics'"'67 Lydia Leung, Sunny Chu, Luis Ng, Raymond To, Enboa Wu Material and Packaging Technologies Group, Hong Kong Applied Science and Technology Research Institute Co. Ltd (ASTRI), HONG KONG
P120*	Laminates for MEMS and BioMEMS "6: Mark Bachman, GP. Li Department of Electrical Engineering and Computer Science, University of California, Irvine, USA
P107*	Opportunities on Prolong Battery Stand-by Time """75 Tam Yee Kam Daphne ¹ , Chen Haibin ² , Wu JingShen ² ¹ NXP Semiconductors, HONG KONG ² The University of Hong Kong Science and Technology, HONG KONG
P041	Inductive Link Design with Optimal Transfer Efficiency and a High CMRR ""7: Yi-Chieh Lin, Tzyy-Sheng Horng, Lih-Tyng Hwang Department of Electrical Engineering, National Sun Yat-Sen University, TAIWAN
16:40-17:00 <i>P003</i> ⁺	In-line Monitoring of the Change of Residual Stress in Nano-Scale Transistors during Their Thin-Film Processing and Packaging ""84 Hironori Tago ¹ , Ken Suzuki ² , Hideo Miura ² ¹ Dept. of Nanomechanics, Graduate School of Engineering, Tohoku University, Sendai, Japan Fracture and Reliability Research Institute, Graduate School of Engineering, Tohoku University, Sendai, Japan 6-6-11-716, Aoba, Aramaki, Aoba-ku, Sendai, Japan
P056	Development of thermal fatigue sensor for electrical and electronic equipment 89 Yuya MINAKATA ¹ , Qiuang YU ¹ , Kanji Takagi ² ¹ Yokohama National University, Yokohama, JAPAN ² OMRON Automotive Electronics Co, Ltd., JAPAN

Session I-c TSV

<i>P103*</i>	Supply Chains for 3D IC Integration Manufacturing "94 John H. Lau Electronics & Optoelectronics Research Laboratory, Industrial Technology Research Institute (ITRI), TAIWAN
<i>P036</i> ⁺	Warpage, Stresses and KOZ of 3D TSV DRAM Package During Manufacturing Processes"9; P. S. Huang1, M. Y. Tsai ¹ , C. Y. Huang ¹ , P. C. Lin ² , Lawrence Huang ² , Michael Chang ² , Steven Shih ² , J.P. Lin ² ¹ Department of Mechanical Engineering, Chang Gung University, TAIWAN ² Technology Development Div, Nanya Technology Co., TAIWAN
P076	A 3D Integration Testing Vehicle with TSV Interconnects ^{"""} : 6 Tiwei Wei ¹ , Qian Wang ¹ , Ziyu Liu ¹ , Yinan Li ³ , Dejun Wang ³ , Tao Wang ¹ , Jian Cai ^{1,2} ¹ Institute of Microelectronics, Tsinghua University, CHINA ² Tsinghua National Laboratory for Information Science and Technology, CHINA ³ Faculty of Electronic information and Electrical Engineering, Dalian University of Technology, CHINA
P106	Through Silicon Via (TSV) Redundancy – A High Reliability, Networking Product Perspective "":; Poh Choon Chew, Li Li, Jie Xue, William Eklow
<i>P013</i> ⁺	Cisco Systems, Inc Evaluation of the Crystallographic Quality of Electroplated Copper Thin-Film "'; 6 Interconnections Embedded in TSV Structures Ryosuke Furuya ¹ , Ken Suzuki ² , and Hideo Miura ² ¹ Dept. of Nanomechanics, Graduate School of Eng., Tohoku University, JAPAN ² Fracture and Reliability Research Institute, Graduate School of Eng., Tohoku University, JAPAN
<i>P032</i> ⁺	Silicon Substrate with TSV for Light Emitting Diode Packaging "322 Zhicheng Lv ^{1,2,4} , Xiaogang Liu ^{2,3} , Liang Yang ^{2,3} , Jiaojiao Yuan ^{2,3} , Xuefang Wang ^{2,3} , Sheng Liu ^{2,3} ¹ School of Optoelectronic Science and Engineering, Huazhong University of Science and Technology, CHINA ² MOEMS Division, Wuhan National Lab for Optoelectronics, Huazhong University of Science & Technology, CHINA ³ Institute of Microsystems, State Key Lab of Digital Manufacturing Equipment & Technology, School of Mechanical Science and Engineering, Huazhong University of Science & Technology, CHINA ⁴ Huazhong University of Science and Technology, F101 Wuhan National Lab for Optoelectronics, CHINA
<i>P001</i>	Assembly Analysis of Cu/Ni/SnAg Microbump for Stacking Thin Chips in a Fine Pitch Package Using a Wafer-level Underfill "326 Chang-Chun Lee ¹ , Tsung-Fu Yang ² , Kuo-Shu Kao ³ , Ren-Chin Cheng ³ , Chau-Jie Zhan ³ ¹ Research and Development Center for Microsystem Reliability Department of Mechanical Engineering, Chung Yuan Christian University, TAIWAN ² Electronics division, Business Group III, Topco Scientific Co., LTD. ³ Assembly and Reliability Technology Department, Industrial Technology Research Institute.
<i>P008</i>	Current Stressing Effects on Interfacial Reaction Characteristics of Fine-Pitch Microbump "333 Jong-Myeong Park, Jong-Jin Park, Sung-Hyuk Kim, Young-Bae Park School of Materials Science and Engineering, Andong National University, KOREA
P059	Employment of a bi-layer of Ni(P)/Cu as diffusion barrier for the 3D integration bonding "P IC Byunghoon Lee and Hoo-jeong Lee School of Advanced Materials Science and Engineering, Sungkyunkwan University, Suwon, South Korea

Session I-d Solders

P0 77*	High-Speed, Low-Power Device Trend and Low-k Layer Delamination "336 Hirofumi Nakajima Renesas Electronics Corporation, Japan
P063	Microstructural Analysis of Lead-free Solder Joint under Thermo-mechanical Loading "33: Kuo-Kang Hung, Mei-Ling Wu Department of Mechanical & Electro-Mechanical Engineering National Sun Yat-Sen University, TAIWAN
P016	Effect of additive elements on tensile, creep and low cycle fatigue strength for SnBi solders "344 Sho NAKANO, Masao SAKANE, Hiroaki HOKAZONO, Mitsuo YAMASHITA Department of Science and Engineering Ritsumeikan University, JAPAN
P080	The Effect of Gold Concentration through a Single Dynamic Wave Soldering Process with respect to PCB Assembly "349 F. Che Ani ¹ , A. Jalar ¹ , M.S. Abdul Aziz ² , M.Z. Abdullah ² , P. Rethinasamy ³ , ¹ Institute of Microengineering and Nanoelectronics, Universiti Kebangsaan Malaysia, MALAYSIA. ² School of Mechanical Engineering, Universiti Sains Malaysia, MALAYSIA. ³ Celestica (M) Sdn. Bhd., Industrial Tech. Kulim, Kedah, MALAYSIA.
<i>P095*</i>	The Interfacial Interaction of Ti/Ni/Ag/Au Multilayer under Thermal Cycling Test "358 <i>Fu-Jung Yeh, Tsung-Chieh Chiu, Kwang-Lung Lin</i> Department of Materials Science and Engineering, National Cheng Kung University, T4IW4N
<i>P092</i>	The Evolution of IMCs' Morphologies and Types in SAC and SAC+ Solder Bumps during Thermal Shock Process "363 Ying Zhong ¹ , Chun Qing Wang ¹ , J.F.J.M. Caers ² , Xiujuan Zhao ² ¹ State Key Laboratory of Advanced Welding and Joining, Harbin Institute of Technology, CHINA ² Philips Research, Eindhoven, NETHERLANDS
<i>P113</i> ⁺	Assembly and Testing of Thermal Test Chip on Silicon Interposer with Through Silicon Via "367 Ziyu Liu ¹ , Jian Cai ^{1, 2} , Qian Wang ¹ , Xi He ¹ , Shuidi Wang ¹ ¹ Institute of Microelectronics, Tsinghua University, CHINA ² Tsinghua National Laboratory for Information Science and Technology, CHINA
<i>P114</i> ⁺	Localized Heating and Bond Formation at Solder/Cu Interface Induced by Ultrasonic Friction "372 <i>Zhuolin Li¹, Mingyu Li¹, Jongmyung Kim², Hongbae Kim²</i> ¹ Shenzhen Graduate School, Harbin Institute of Technology, CHINA ² Jeonnam Provincial College, SOUTH KOREA
<i>P108</i>	Tin Whisker Mitigation: from Single Layer to Multilayer "'P IC Ting Liu ¹ , Dongyan Ding ¹ , Yu Hu ² , Yihua Gong ² ¹ Shanghai Jiao Tong University, CHINA ² Corporate Technology, Siemens Ltd., CHINA
	Session II-a Materials & Processing (2)
<i>P104*</i>	Parametric Modeling Study of Basic Electrodeposition in Microvias "376 Nadezhda Strusevich, Mayur Patel, Christopher Bailey University of Greenwich, UK
<i>P002</i> ⁺	Effect of the Lattice Mismatch between Copper Thin-film Interconnection Base Material on the Crystallinity of the Interconnection""37; " Chuanhong Fan ¹ , Osamu Asai ¹ , Ken Suzuki ² , Hideo Miura ² ¹ Dept. of Nanomechanics, Graduate School of Eng., Tohoku University, JAPAN ² Fracture and Reliability Research Institute, Graduate School of Eng., Tohoku University,

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011		

<i>P112</i> ⁺	A Facile Fabrication method of Silver Lines on PET with Good Adhesion at Room Temperature""386 Yunxia Jin, Dunying Deng, Yuanrong Cheng, Fei Xiao Fudan University, CHINA
<i>P015</i>	Dependence of packing fraction and surface area of the particles in the composites made by the combination of aluminum oxide and nitride for improving the thermal conductivity "38: <i>Seran Choi, Yuseon Heo, Myeongjin Kim, Yongseon Hwang, Jooheon Kim Chung-Ang University, KOREA</i>
<i>P049</i> ⁺	Carbon Nanotubes Based Composites with High Dielectric Constant and Low Loss "393 Imtiaz Madni ¹ , Shuhui Yu ¹ , Rong Sun ¹ , Shenzhen Institutes of Advanced Technology, Chinese Academy of Sciences, CHINA
P091*	Effects of Surface Treatments on the Performance of High Thermal Conductive Die Attach Adhesives (DAAs) "399 Chenmin LIU, Dong Lu, Xianxin LANG, Ashley Choi, Peter WM Lee Nano and Advanced Materials Institute The Hong Kong University of Science and Technology, Hong Kong, CHINA
<i>P027</i> ⁺	Micro-Texture and Physical Properties of the Cold-sprayed Copper Deposit "3: 4 Yusuke Watanabe, Yuji Ichikawa, Isamu Nonaka, and Hideo Miura Tohoku University, JAPAN
P089	Molding Void Issue and Solution of a Package-in-Package''''3: 8 Yu Chen ¹ , Jian Cai ¹ , Mian Huang ² , Guanqiang Song ³ , Jing Jiang ³ , Lin Tan ¹ , Qian Wang ¹ ¹ Tsinghua University, CHINA ² Institute of Microelectronics of the Chinese Academy of Sciences, CHINA ³ Shennan Circuit Co., Ltd., CHINA
P058	Volume Effect on Interfacial Microstructure and Mechanical Properties of Ni(UBM)/Sn3.0Ag0.5Cu/Ni(UBM) Joints'"3; 3 Jing-Bo Zeng, Guang-Sui Xu, Min-Bo Zhou, Xin-Ping Zhang South China University of Technology, CHINA
	Session II-b Reliability (1)
P007*	Hygrothermal Analysis for the Electrochemical Migration Failure in Multi-Chip Packages during a Highly Accelerated Stress Test""3; 8 Jongguk Choe ¹ , Jae-Won Jang ¹ , Nam-Seog Kim ² , Soon-Bok Lee ¹ ¹ Department of Mechanical Engineering, Korea Advanced Institute of Science and Technology, Republic of Korea ² SK Hynix Inc. Icheon, Gyeonggido, Republic of Korea
<i>P071</i>	Research on Temperature Gradient Effect to Solder Joint Reliability ""422 Zheming Zhang ^{1,2} , Jingshen Wu ^{1,2} ¹ The Hong Kong University of Science and Technology, Hong Kong, CHINA ² Fok Ying Tung Graduate School, The Hong Kong University of Science and Technology, CHINA

P102Reliability Simulation and Structural Optimization for Mechanical Loading ""429
Jia-Shen Lan, Mei-Ling Wu
National Sun Yat-Sen University, TAIWAN

P115⁺ Impact from IMC Thickness on the Reliability of Wire Bonding ""433 *J. Xiao, J. Huang, J. Liao, Y. Lin*

	University of Electronic Science and Technology of China, CHINA
<i>P018</i> ⁺	Effects of Molding Compounds on Warpage and Damage of PBGA after Post Mold Cure "'438 Tatiana M. Lam, Sung Yi Mechanical and Material Engineering Department, Portland State University, Portland, USA
P026*	Feasibility of PBGA Packaging for High Random Vibration Applications "446 Yeong K. Kim ¹ , Do Soon Hwang ² , Jae Hyuk Lim ² ¹ Korea Aerospace University Dukyang Gu, Goyang Si, Kyun-gi Do, 412-791, South Korea ² Korea Aerospace Research Institute, Daejun, 305-806, South Korea
<i>P019</i> ⁺	Effects of Microstructure on Thermal Fatigue Life Prediction of Solder Joints "449 Hiue Tran ¹ , Yin Fun Chua ¹ , Sung Yi ¹ , Phil Geng ² ¹ Portland State University, USA ² Intel Corporation, USA
P031	Development of Innovative Cold Pin Pull Test Method for Solder Pad Crater Evaluation ""457 Qiming Zhang, Chaoran Yang, Mian Tao, Fubin Song, S. W. Ricky Lee, Hong Kong University of Science & Technology, Hong Kong
P061	Ultrasonic Inspection of Package Internal Defects Considering Multiple Interface Effects ""45; Minshu Zhang ¹ , C. C. Jeffery. Lo ² , Shi-Wei Ricky Lee ² ¹ Xiamen University of Technology, CHINA ² Hong Kong University of Science and Technology,Hong Kong, CHINA

Session II-c LED & Power Electronics (1)

Chair: MY Tsai, Chang Gung; Co-chair: Lilin Liu, SYSU

<i>P037</i> *	The Role of Thermal Properties of PCB Substrates in Heat Dissipation of LED Back Light Bars ""466 C. Y. Tang ¹ , J. J. Huang ¹ , Y. L. Peng1, M. Y. Tsai ¹ , and Peter Liang ² ¹ Chang Gung University, TAIWAN ² Nanya Plastics Co., TAIWAN
P109*	Color Consistence Improvement in LED packages ""472 Cell K.Y. Wong ¹ , Stanley Y.Y. Leung ¹ , Lin Niu ¹ , Gongqi Fan ¹ , Xiang Zhou ¹ , Cadmus C.A. Yuan ² , Guoqi Zhang ² , Yanglin Li ⁴ , Menglong Tu ⁴ , Shaofang Wang ⁴ ¹ State Key Laboratory of Solid State Lighting (Changzhou Base), CHINA ² State Key Laboratory of Solid State Lighting, Haidian, CHINA ³ DIMES, Delft University of Technology, the Netherlands ⁴ Ledman Optoelectronic Co. Ltd, CHINA
P039	A method for geometry control of phosphor layer in high-power white LEDs by package structure ""477 Huai Zheng, Xing Fu, Bulong Wu, Sheng Liu, and Xiaobing Luo Huazhong University of Science and Technology, CHINA
P068	LED Wafer Level Packaging with a Remote Phosphor Cap ""482 Huihua Liu, Rong Zhang, Jeffery C. C. Lo, S. W. Ricky Lee Hong Kong University of Science and Technology, Hong Kong
P025	A Thermal Performance Assessment of Panel Type Packaging (PTP) Technology for High Efficiency LED'''487 Yen-Fu Su ¹ , Yu-Hsiang Yang ¹ , Wen-Kun Yang ² , Kuo-Ning Chiang ^{1,3} ¹ National Tsing Hua University, Hsinchu, TAIWAN ² King Dragon International Inc., British Virgin Islands

³National Center for High-Performance Computing

P064*	High Bright White LED Packaging Systems Using Unique Vacuum Printing Technology (VPES) "'492 Atsushi Okuno, Yoshiteru Miyawaki, Dongxu Wang, Osamu Tanaka SANYU REC CO.,LTD,JAPAN
<i>P093*</i>	The Investigation of LED's Reliability Through Highly Accelerated Stress Testing Methods "496 <i>Lilin Liu, Jianfu Yang, Gang Wang Sun Yat-Sen University,, CHINA</i>
<i>P099</i>	Convenient fabrication of Composites with Aqueous Synthesized Quantum Dots for LED Encapsulation "'499 Lei Zhang, Haibin Chen, Jingshen Wu Center for Engineering Materials and Reliability, Fok Ying Tung Graduate School, The Hong Kong University of Science and Technology
<i>P105</i> ⁺	White LED devices with nearly uniform space-color distribution through nanoparticle usage "4: 4 <i>Mingyang Wu, Lilin Liu, Gang Wang Sun Yat-Sen University, CHINA</i>
Session II-d Nano & Emerging Technologies (1)	

P051	Transparent Functionalized Zinc Oxide/Epoxy Nanocomposite with High Thermal Performance for High-Power Light-Emitting Diodes "4: 8 Min Zhang, Kai Zhang, Xinfeng Zhang, Chen Yang, Matthew Ming-Fai Yuen The Hong Kong University of Science and Technology, Hong Kong, CHINA
<i>P033</i> +	Hard Mold UV Nanoimprint Lithography Process "'4; 4 Yinsheng ZHONG, Matthew. M. F. YUEN The Hong Kong University of Science and Technology, Hong Kong, CHINA
<i>P048</i> ⁺	Different morphologies of Nano-ZnO affection on properties of transparent epoxy resin encapsulants ¹¹⁴ ; 9 <i>Chongnan Peng^{1,2}, Guoping Zhang¹*, Rong Sun¹, Ricky Lee³</i> ¹ Shenzhen Institutes of Advanced Technology, Chinese Academy of Sciences. CHINA ² Shenzhen University, CHINA ³ The Hong Kong University of Science and Technology, Hong Kong, CHINA
P050	Carbon Nanotubes Based Composites with High Dielectric Constant and Low Loss "523 Imtiaz Madnil, Shuhui Yu, Rong Sun Shenzhen Institutes of Advanced Technology, Chinese Academy of Sciences, CHINA
P054	Preparation And Performance Research On The Si ₃ N ₄ @SiO ₂ /PI Nanocomposite "529 Jing Qin ^{1,2} , Guoping Zhang ¹ , Rong Sun ¹ , Chingping Wong ^{1,3} ¹ Shenzhen Institutes of Advanced Technology Chinese Academy of Science, CHINA ² Shenzhen University, CHINA. ³ Chinese University of Hong Kong, CHINA
P009	Development of Highly Conductive Inks for Smart Textiles "533 Masahiro Inoue ¹ , Yasunori Tada ¹ , Hiroaki Muta ² , Yamato Hayashi ³ , Tomohiro Tokumaru ⁴ ¹ Gunma University, JAPAN ² Osaka University, JAPAN ³ Tohoku University, JAPAN ⁴ Bio Signal Co., Ltd. JAPAN
P065	An Investigation on Secondary EFO Copper Wire – from a Nanoscale Perspective View"537 Hsiang-Chen Hsu, Jih-Hsin Chien, Chen-Yi Wang, Cheng-Che Liu, Shen-Li Fu, Miin Shyan

	Bair I-Shou University, TAIWAN
	Wet-chemical Synthesis of the Size-controlled BaTiO3 Nanoparticles for Embedded
P062	Capacitors 545 Enhe Zhang ^{1,2,} Suibin Luo ¹ , Wenhu Yang ¹ , Shuhui Yu ¹ , Rong Sun ¹ , Yubao Zhao ² ¹ Shenzhen Institutes of Advanced Technology, Chinese Academy of Sciences, CHINA ² University of South China, CHINA
<i>P022</i> ⁺	Mechanical fastening to enable room temperature packaging for LOCs based on biocompatible hydrogel thin film "547 Weiwei Zhao ¹ , Changqing Liu ¹ , Cristina Lenardi ² , Tommaso Santaniello ^{1,2} , Fengshun Wu ³ ¹ Loughborough University, Loughborough, UK
	² University of Milan, Milan, ITALY ³ Huazhong University of Science and Technology
	Session III-a Interconnect & Bonding
P090*	Process Considerations of TC-NCP Fine-pitch Copper Pillar FC Bonding "552 Y.M. Cheung, Ka San Lam, Giuseppe Y. Mak, Dewen Tian, Ming Li ASM Technology Hong Kong, Hong Kong, China
D 110	Low-Temperature Bonding Method Based On Metallic Microcone Array For Interconnection Application "559 <i>Qin Lu, Zhuo Chen, Liming Gao,</i> * <i>Ming Li</i>
<i>P110</i>	State Key Laboratory of Metal Matrix Composites, Key Laboratory for Thin Film and Microfabrication Technology of the Ministry of Education, School of Material Science and Engineering, Shanghai Jiao Tong University, China
P006	Low Temperature Bonding of Piezoelectric Single Crystal Materials for Miniaturized High Resolution Ultrasound Transducers""563 Jack Hoy-Gig Ng ¹ , Robert T. Ssekitoleko ² , Hoang-Vu Nguyen ³ , Knut E. Aasmundtveit ³ , Christine E. M. Démoré ⁴ , Sandy Cochran ⁴ and Marc P.Y. Desmulliez ¹ ¹ MIcroSystems Engineering Centre (MISEC), Institute of Sensors, Signals and Systems (ISSS), Heriot-Watt University, Scotland, UK
	² Department of Bioengineering, University of Strathclyde, Glasgow, Scotland, UK ³ Department of Micro and Nano Systems Technology (IMST), Vestfold University College, Norway ⁴ Institute for Medical Science and Technology (IMSaT), University of Dundee, Scotland, UK
<i>P028</i> ⁺	An Atomistic Scale Study on Solidification in Ultrafine Interconnects "567 Zhiyong Wu ¹ , Zhiheng Huang ¹ , Paul Conway ² , and Qingfeng Zeng ³ ¹ School of Physics and Engineering, Sun Yat-sen University, China ² Wolfson School of Mechanical and Manufacturing Engineering, Loughborough University,
	³ School of Materials Science and Engineering, Northwestern Polytechnical University, China
<i>P017</i> ⁺	Development of low temperature Chip-on-Flex (COF) bonding process of 100°C ""574 Sun-Chul Kim and Young-Ho Kim Division of Materials Science & Engineering, Hanyang University, Korea
P085	Development and Qualification of Copper Wire Bond Process for Automotive Applications"577 Pey Fang Hiew, Yin Kheng Au, Poh Leng Eu Freescale Semiconductor (M) Sdn. Bhd., Malaysia
P086	Importance of Cu/Al Intermetallic Coverage in Copper Wire Bonding with Sensitive Pad Structure""582 Tracy Jia Lin Yap, Yin Kheng Au, Poh Leng Eu

P088Systematic Pd Cu Wire Bond Recipe Development Flow for Successful Qualification Result "587P088Law Lai Cheng, Wong Boh Kid, Hiew Pey Fang, Eu Poh Leng
Freescale Semiconductor, (M) Sdn. Bhd., Malaysia

Session III-b Reliability (2)

P057*	Solder Volume Effects on Fatigue Life of BGA Structure Cu/Sn-3.0Ag-0.5Cu/Cu Interconnects "58; Hong-Bo QIN ¹ , Xun-Ping LI ^{1,2} , Xin-Ping ZHANG ¹ ¹ Smart Materials and Electronic Packaging (SMEP), School of Materials Science and Engineering, South China University of Technology, Guangzhou, China ² Science and Technology on Reliability Physics and Application of Electronic Component Laboratory, the 5 th Electronics Research Institute of Ministry of Information Industry, Guangzhou, China
P045	Effect of interfacial reaction layer on the brittle fracture of the SAC305 solder joint on ENIG and ENEPIG surface finish'''598 Sang-Hyun Kwon ¹ , Kang-Dong Kim ² , Deok-Gon Han, Tae-Hyun Sung, Chang-Woo Lee ¹ , and Sehoon Yoo ¹ ¹ Korea Institute of Industrial Technology, KOREA ² Samsung Electro-Mechanics Co., LTD, KOREA
P055	Packaging of Microelectronics for Thermo-Mechanical Environments "59; Ming-Han Wang, Mei-Ling Wu Department of Mechanical Engineering, National Sun Yat-Sen University, Kaohsiung, Taiwan
<i>P012</i> ⁺	Improvement of the Reliability of Thin-Film Interconnections Based on the Control of the Crystallinity of the Thin Films "5: 5 Osamu Asai, Naokazu Murata, Ken Suzuki, and Hideo Miura Tohoku University, Sendai, JAPAN
P035*	Reliability evaluation of a new 3D SIC package by FEM and thermal-strain measurement with digital image correllation using SEM ""P IC Toru Ikeda ¹ , Masatoshi Oka ² , and Noriyuki Miyazaki ² , Hiroyuki Tanaka ³ , Takuya Hatao ⁴ ¹ Kagoshima University, Kagoshima, Japan ² Kyoto University, Kyoto, Japan ³ Sumibe Research Co., Ltd., Utsunomiya, Japan ⁴ Sumitomo Bakelite Co., Ltd., Utsunomiya, Japan
P094*	Investigation of Rework for Straddle Mount Connectors "5: : Jeffery Li ¹ , Fubin Song ¹ , Khoo KoK Wei ¹ , James Huang ¹ , Alex Chen ² , PK Pu ³ , Sven Peng ³ ¹ Celestica, Song Shan Lake, China, ² Celestica, Toronto, Canada. ³ IBM Corporation, ShenZhen, China
<i>P029</i> ⁺	Effects of Microstructure on Vacancy and Stress Distributions in Micro Joints under Current Stressing "5; 5 Hua Xiong ¹ , Zhiheng Huang ¹ , Paul Conway ² , Qingfeng Zeng ³ ¹ School of Physics and Engineering, Sun Yat-sen University, 135 West Xingang Road, Guangzhou, China ² Wolfson School of Mechanical and Manufacturing Engineering, Loughborough University, U.K. ³ School of Materials Science and Engineering, Northwestern Polytechnical University, China

<i>P023</i> ⁺	Fatigue Life and Reliability Prediction of Electronic Packages under Thermal Cycling Conditions through FEM Analysis and Acceleration Models"623 <i>Xuhua Huang, Wen-Fang Wu and Po-Lun Chou</i> <i>National Taiwan University, TAIWAN</i>	
Session III-c LED & Power Electronics (2)		
P084*	LED Device & SSL packaging trends study by x-ray analysis'""P IC T. Onishi Grand Joint Technology Ltd.	
P096	Thermal performance and placement design of LED array package on PCB "629 K.C. Yung, H.M. Liem, H.S. Choy Department of Industrial and Systems Engineering, the Hong Kong Polytechnic University, Hong Kong	
<i>P097</i> ⁺	Anomaly Detection for Chromaticity shift of High Power White LED with Mahalanobis Distance Approach "634 Jiajie Fan ¹ , Kam-Chuen Yung ¹ , Michael Pecht ² ¹ PCB Technology Center, Department of Industrial and Systems Engineering, The Hong Kong Polytechnic University, Hong Kong ² Center for Advanced Life Cycle Engineering, University of Maryland, USA	
<i>P044</i>	Study on Thermal Design due to Downsizing of Power Module Using Coupled Electrical-Thermal-Mechanical Analysis""639 Yasutaka YAMADA, Qiang YU, Tomohiro TAKAHASHI Yusuke TAKAGI Yokohama National University, Japan	
P053	A Study on Evaluation Method of New Packaging Structure for High-Temperature Power Device"'646 Akihiro HIGUCHI, Qiang YU, Toshikazu OSHIDARI, Mingliang CUI Yokohama National University, Japan	
16:00-16:20 <i>P081</i>	Novel Substrate Technology for IPM (Intelligent Power Module) Applications: Structural, Thermal and Electrical Characteristics"'652 <i>Kwang-Soo Kim¹</i> , Young-Ki Lee ¹ , Young-Hoon Kwak ¹ , Ji Hyun Park ¹ , Job Ha ¹ , Ga-Young Shin ² , Bum-Seok Suh ¹ ¹ Samsung Electro-Mechanics Co., LTD., Suwon, Korea ² Department of Chemistry, Hanyang University, Seoul, Korea	
P119	IGBT Power Module Packaging for EV Applications ""655 Chun-Kai, Liu, Yu-Lin Chao, June-Chien Chang, Wei Li, Chih-Ming Tzeng, Rong-Chang Fang, Kuo-Shu Kao, Tao-Chih Chang, Chang-Sheng Chen, Wei-Chung Lo Electronics and Opto-Electronics Laboratories/Industrial Technology Research Institute, Taiwan	
P082	Packaging of SiC-SBD for High Temperature Operation "659 Zarel Valdez-Nava ^{1,2} , Masahiro Kozako ³ , Sorin Dinculescu ^{1,2} , Ichiro Omura ³ , Masayuki Hikita ³ , Thierry Lebey ^{1,2} ¹ Université de Toulouse, France. ² CNRS, France. ³ Kyushu Institute of Technology, Japan	
P118	Dual-phase solid-liquid interdiffusion bonding, a solution for the die attachment of WBG power module assembly""663 <i>Tao-Chih Chang, Jing-Yao Chang, Tung-Han Chuang</i> <i>Industrial Technology Research Institute, Taiwan</i>	

Session III-d Nano & Emerging Technologies (2)

<i>P070*</i>	Multiscale Modeling of Thermomechanical Behavior of Lead-Free Solders and Solder/Cu Interfaces "P IC Feng Gao, Jianmin Qu Department of Civil and Environmental Engineering Department of Mechanical Engineering Northwestern University Evanston, USA
<i>P004</i>	Highly Sensitive Strain Sensor Using Carbon Nanotube "'668 Hiroshi Kawakami ¹ , Ken Suzuki ² , Hideo Miura ² ¹ Dept. of Nanomechanics, Graduate School of Eng., Tohoku University, Japan ² Fracture and Reliability Research Institute, Graduate School of Eng., Tohoku University, Japan
<i>P014</i> ⁺	Highly Transparent Conducting Graphene Films Produced by Langmuir Blodgett Assembly as Flexible Electrodes "673 Xiuyi Lin, Jingjing Jia, Nariman Yousefî, Xi Shen, Jang-Kyo Kim Department of Mechanical Engineering, The Hong Kong University of Science and Technology, Hong Kong
<i>P066</i> ⁺	Fabrication of One-dimensional CuO Nanocrystals via Pulsed Wire Explosion: Structural, Optical and Electronic Characterizations'"'678 Shutesh Krishnan, A.S.M.A Haseeb, Mohd. Rafie Department of Mechanical Engineering University of Malaya,, Malaysia
<i>P116</i> ⁺	Pressureless low temperature sintering of Ag nanoparticles for interconnects"'682 Shuai Wang ¹ , Hongjun Ji ¹ , Mingyu Li ¹ , Jongmyung Kim ² , Hongbae Kim ² Shenzhen Graduate School, Harbin Institute of Technology, China. ² Jeonnam Provincial College, South Korea
P111	Preparation of Copper Nanoparticles with Low Sintering Temperature "686 Dunying Deng, Yunxia Jin, Yuanrong Chen, Tianke Qi, Fei Xiao Fudan University, CHINA
P083	RFID device packaging trends study by tear down ""P IC T. Onishi Grand Joint Technology Ltd.
P 117	An Assessment Method for Cu Wire Bond-pads "P IC Dewen Tian, Janardhanan Pillai Madhukumar, Ming Li ASM Pacific Technology, Hong Kong, China
P08 7	Effect of Chemical Etching Solution on Cu/Al IMC Result"""68: Wong Boh Kid, Eu Poh Leng, Yow Kai Yun Freescale Semiconductor, (M) Sdn. Bhd., Malaysia